

CLAIMS

1. An electrical grounding structure for an electronic device enclosure, the electrical grounding structure comprising:
 - 5 a ground point;
 - a ground point coupling element coupled to the ground point;
 - a first conductive surface of a device enclosure, conductively isolated from the ground point; and
 - a second conductive surface, conductively coupled to the ground point
- 10 coupling element and physically separated from the first conductive surface, positioned so as to capacitively couple to the first surface with a pre-determined capacitance within an RF band of interest.
2. The electrical grounding structure according to claim 1, further comprising an
- 15 electronic device containing the ground point, the first conductive surface and the second conductive surface, the electronic device being one of a wireless device and a portable computing device.
3. The electrical grounding structure according to claim 1, the ground point
- 20 located in substantial proximity to at least one of an antenna RF drive point and an RF amplifier output.

4. The electrical grounding structure according to claim 1, the ground point coupling element being reactively coupled to and conductively isolated from the ground point.

5 5. The electrical grounding structure according to claim 1, further comprising at least one additional conductive surface, each of the at least one additional conductive surface conductively isolated from the first conductive surface and positioned so as to capacitively couple to the first surface with a respective pre-determined capacitance, and each of the at least one additional conductive surface being coupled to the ground
10 point.

6. The electrical grounding structure according to claim 5, wherein each of the at least one additional conductive surface is coupled to the ground point through a respective coupling element that has a respective pre-determined impedance.

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7. The electrical grounding structure according to claim 1, further comprising:
at least one additional ground point; and
at least one additional conductive surface, each of the at least one additional conductive surface conductively isolated from the first conductive surface and
20 positioned so as to capacitively couple to the first surface with a respective pre-determined capacitance, and each of the at least one additional conductive surface being coupled to at least one of the ground point and at least one of the at least one additional ground point.

8. The electrical grounding structure according to claim 1, the second conductive ground point coupling element being conductively coupled to the ground point.
- 5 9. The electrical grounding structure according to claim 8, wherein the ground point coupling element comprises a yieldable contact, conductively connected to the second conductive surface, that yieldably engages the ground point.
- 10 10. The electrical grounding structure according to claim 1, further comprising a conductive element that forms at least part of a conductive path conductively coupling the second conductive surface to the ground point coupling element, the conductive element having an inductance that operates in conjunction with the pre-determined capacitance to exhibit a pre-defined impedance between the ground point and the first conductive surface near at least one RF frequency.
- 15 11. The electrical grounding structure according to claim 10, further comprising a yieldable contact that yieldably engages the ground point, the second conductive surface engaging a first end of the conductive element and the yieldable contact engaging a second end of the conductive element, conductively connected to the
- 20 second conductive surface.

12. The electrical grounding structure according to claim 1, further comprising a substantially non-conductive support structure, the second conductive surface being attached to the substantially non-conductive support structure and the substantially non-conductive support structure engaging the first conductive surface so as to
5 maintain a pre-defined separation between the first conductive surface and the second conductive surface.

13. The electrical grounding structure according to claim 12, further comprising a conductive element that forms at least part of a conductive path conductively coupling
10 the second conductive surface to the ground point, the conductive element having an inductance that operates in conjunction with the pre-determined capacitance to exhibit a pre-defined impedance between the ground point and the first conductive surface near at least one RF frequency.

15 14. The electrical grounding structure according to claim 13, further comprising a yieldable contact that engages the conductive element at a second end, the yieldable contact yieldably engages the RF ground point.

15. The electrical grounding structure according to claim 14, wherein the second
20 conductive surface, conductive element and yieldable contact form a yieldable clip that is formed from a yieldable, conductive material, the yieldable clip adapted to attach to the substantially non-conductive surface.

16. A wireless communications section that provides an RF ground to an enclosure, the wireless communications section comprising:
- at least one of a receiver that wirelessly receives transmitted signals and a transmitter that wirelessly transmits signals; and
 - 5 an RF grounding structure, comprising:
 - a ground point;
 - a first conductive surface of a device enclosure, conductively isolated from the ground point; and
 - a second conductive surface, conductively coupled to the ground point
 - 10 and physically separated from the first conductive surface, positioned so as to capacitively couple to the first surface with a pre-determined capacitance within an RF band of interest.
17. The wireless communications section according to claim 16, further
- 15 comprising at least one antenna coupled to the at least one receiver and transmitter.

18. A wireless device, comprising:
- a device enclosure;
 - at least one of an receiver that wirelessly receives transmitted signals and a transmitter that wirelessly transmits signals;
- 5 a baseband processing portion, communicatively coupled to the at least one receiver and transmitter, that processes at least one of data, voice, image and video signals in order to interface with at least one of the receiver and the transmitter;
- an RF grounding structure, comprising:
 - a ground point;
- 10 a first conductive surface of the device enclosure, conductively isolated from the ground point; and
- a second conductive surface, conductively coupled to the ground point and physically separated from the first conductive surface, positioned so as to capacitively couple to the first surface with a pre-determined capacitance
- 15 within an RF band of interest.